## Compal LA-H32AP

Herschel 15 GPP53

**Schematic Document** 

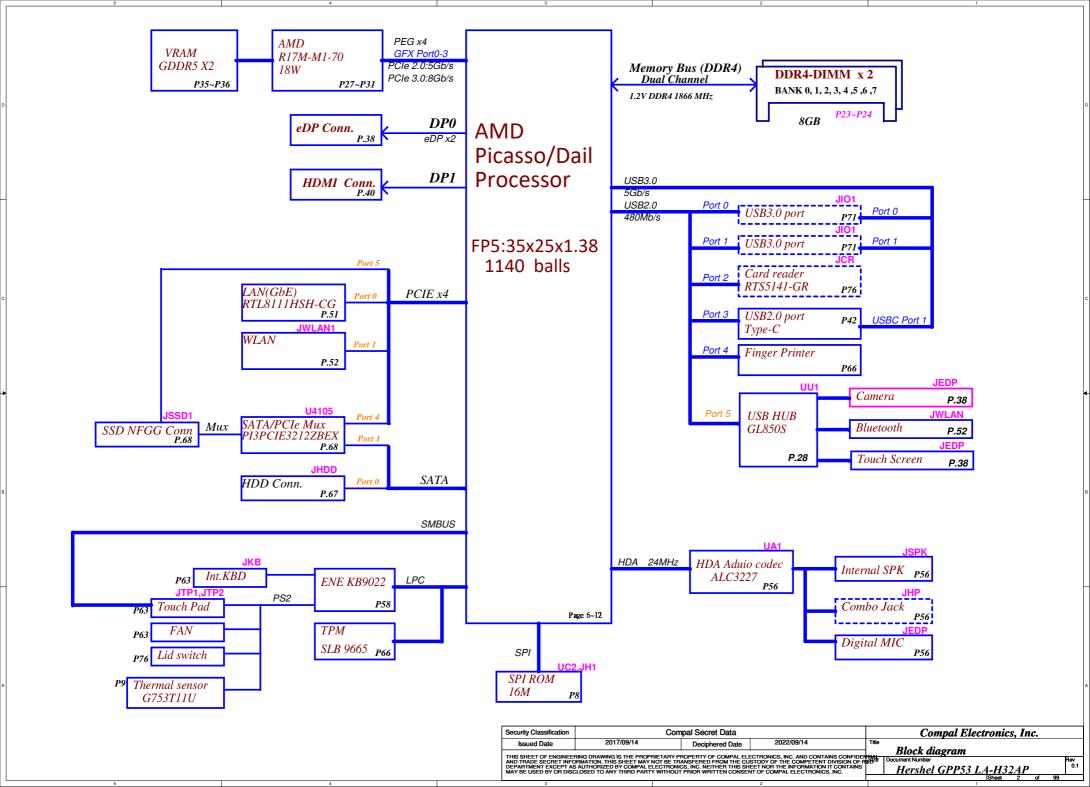
AMD APU Picasso/Dali

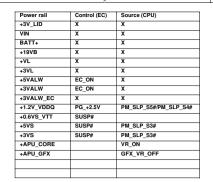
**AMD GPU R17M-M1-70 (Radeon 530)** 

2019/11/01

**Rev: 0.2** 

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APU\_SCLK0 APU\_SDATA

APU\_SMB\_SCLK1 APU\_SMB\_SDAT1

R=1K

EC\_SMB\_CK1 EC\_SMB\_DA1

**CPU** 

UK1:+3VALW EC

EC

+3VALW

R=2.2K

+3V\_SMBUS R=2.2K

R=100

@ is NO SMT part (empty)

short@: short pad, don't pop.

@EMI@,@ESD@,@RF@: Reserve, don't pop.

R=10K

APU External

Thermal Sensor

GPU

RF@: RF team request, must add.

EMI@: EMI team request, must add.

ESD@: ESD team request, must add.

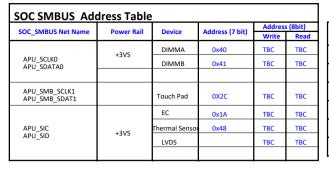
LVDS@: Support LVDS panel.

eDP@: Support eDP panel.

PX@: GPU BOM config.

SO-DIMM A

SO-DIMM B



## <USB Port>

USB3.0 Port	DESTINATION	USB2.0 Port	DESTINATION
0 - 0	Type C	0 - 0	USB3 Type A
0 - 1	Type C	0 - 1	USB3 Type A
0 - 2	USB3 Type A	0 - 2	Card Reader
0 - 3	USB3 Type A	0 - 3	Type C
1 - 0 T1 only		1 - 0	FPR
		1-1	USB HUB

Symbol Note:

: means Digital Ground

: means	Analog	Ground	
	: means	: means Analog	: means Analog Ground

SMBUS Port 1

+3VALW\_EC CHGR

Power Rail

NPU Int sensor OGPU Int senso +3VS

Device

hermal Sensor

0x98 0x82 APU External 0x48 0x90

Address (7 bit)

Address (8bit)

Write Read

TBC

0x99

0x83

0x91

TBC

<PCI-E.SATA.CLK>

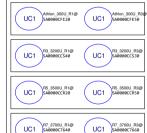
0. =,0.	~, <b>C</b>			
	PCI-E	SATA	DESTINATION	CLK
	0		LAN	CLK1
	1		WLAN	CLK2
T1 only	2		Х	
T1 only	3		Х	
	4		PCI-E SSD	CLK3
	5		PCI-E SSD	CLK3
T2 SATA only	6	0	HDD	
T2 SATA only	7	1	SSD or ODD	

CLK0 GFX GPU

**EC SMBUS Address Table** 

EC\_SMBUS Port

SMBUS Port 2















10/31 Remove reserved VGA thermal sensor (UV13) and other part, net nam	EC_SMB_CK3 EC_SMB_DA3		R=2.2K	GPU External Thermal Sensor	
		10/31 Remove reserve	d VGA thermal sens	or (UV13) and othe	r part, net name

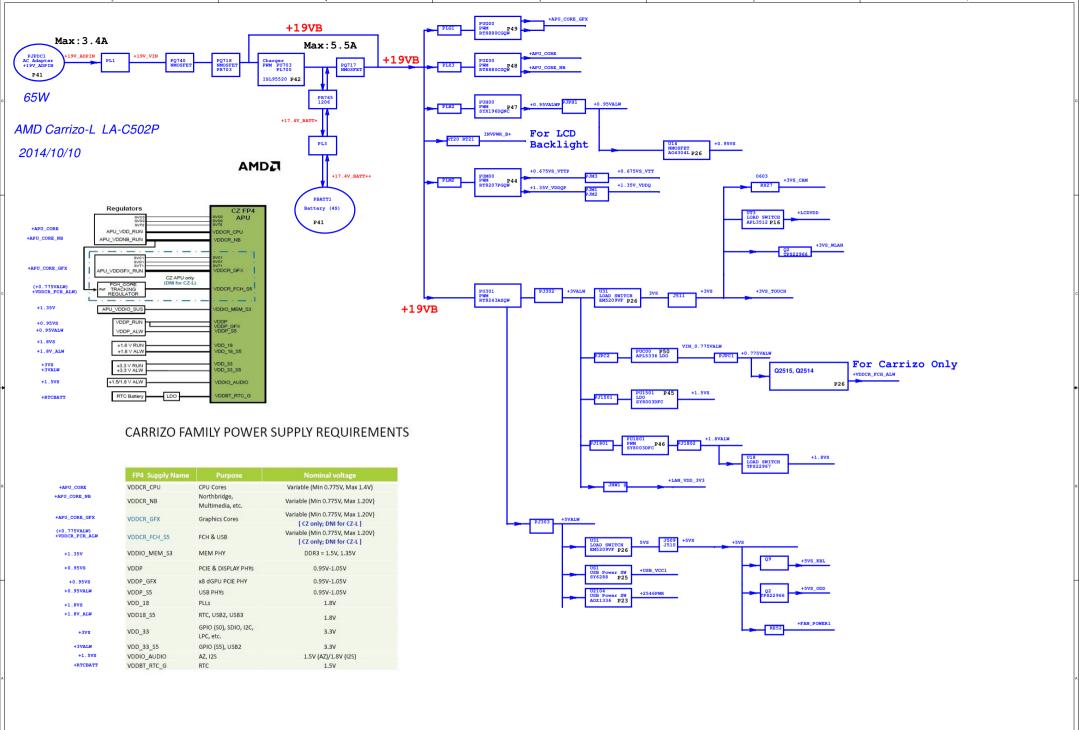
+3VS VGA

R=2.2K

BAT

Charger

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